Materials and Finish
Shell: copper alloy, Plating: tin or tin/lead over copper
Insulator: UL94V-0 rated PBT thermoplastic
Contact Material: phosphor bronze
Contact Plating Options:
- Standard - gold flash on contact area, 120u" tin/lead on solder tails, all over 50u" nickel underplate
- -30 Option - 30u" gold on contact area, 120u" tin/lead on solder tails, all over 50u" nickel underplate

Electrical Specifications
Rated Voltage: 30V AC (rms)
Contact Current Rating: 1A max.
Contact Resistance: 30 milliohms max.
Insulation Resistance: 1000 Megohms min.
Dielectric Withstanding: 500V AC
Operating Temperature: -25°C to 80°C

Mechanical Specifications
Mating Force: 3.57kg max.
Unmating Force: 1.02kg min.

Recommended PCB Layout (top view)

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Contact Area Plating Finish</th>
<th>Insulator Color</th>
</tr>
</thead>
<tbody>
<tr>
<td>KUSB-SL-AS1N-W</td>
<td>Gold Flash (standard)</td>
<td>White</td>
</tr>
<tr>
<td>KUSB-SL-AS1N-W30</td>
<td>30u&quot; Gold (30 option)</td>
<td></td>
</tr>
<tr>
<td>KUSB-SL-AS1N-B</td>
<td>Gold Flash (standard)</td>
<td>Black</td>
</tr>
<tr>
<td>KUSB-SL-AS1N-B30</td>
<td>30u&quot; Gold (30 option)</td>
<td></td>
</tr>
</tbody>
</table>

Tolerances
XX ± 0.35
XXX ± 0.25
Unless Stated
Otherwise

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